STB38N65M5, STP38N65M5, STW38N65M5

Datasheet

N-channel 650 V, 73 mΩ typ., 30 A MDmesh M5 Power MOSFETs in a D²PAK, TO-220 and TO-247 packages

Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STB38N65M5	650 V	95 mΩ	30 A
STP38N65M5			
STW38N65M5			

- Higher V_{DSS} rating
- Higher dv/dt capability
- Excellent switching performance
- Extremely low $R_{DS(on)}$
- 100% avalanche tested

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs based on the MDmesh M5 innovative vertical process technology combined with the well-known PowerMESH horizontal layout. The resulting products offer extremely low on-resistance, making them particularly suitable for applications requiring high power and superior efficiency.

Product status links
STB38N65M5
STP38N65M5
STW38N65M5

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	±25	V
I_D	Drain current (continuous) at T_C = 25 °C	30	A
I_D	Drain current (continuous) at T_C = 100 °C	19	A
I_{DM}(1)	Drain current (pulsed)	120	A
P_{TOT}	Total power dissipation at T_C = 25 °C	190	W
dv/dt(2)	Peak diode recovery voltage slope	15	V/ns
dv/dt(3)	MOSFET dv/dt ruggedness	50	V/ns
T_{stg}	Storage temperature range	-55 to 150	°C
T_J	Maximum operating junction temperature	150	°C

1. *Pulse width limited by safe operating area.*
2. *I_{SD} ≤ 30 A, di/dt ≤ 400 A/µs; V_{DS} (peak) < $V_{(BR)DSS}$, V_{DD} = 400 V.*
3. *V_{DS} ≤ 520 V.*

Table 2. Thermal data

Symbol	Parameter	Value			Unit
		D^2PAK	TO-220	TO-247	
R_{thJC}	Thermal resistance, junction-to-case	0.66			°C/W
R_{thJA}	Thermal resistance, junction-to-ambient	30(1)	62.5	50	°C/W

1. *When mounted on a standard 1 inch^2 area of FR-4 PCB with 2-oz copper.*

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_J max.)	8	A
E_{AS}	Single pulse avalanche energy (starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	660	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified.

Table 4. On/off states

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0 V	650	-	-	V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 650 V	-	-	1	µA
		V_{GS} = 0 V, V_{DS} = 650 V, T_C = 125 °C(1)	-	-	100	µA
I_{GSS}	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V	-	-	±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 15 A	-	73	95	mΩ

1. *Specified by design, not tested in production.*

Table 5. Dynamic

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 100 V, f = 1 MHz, V_{GS} = 0 V	-	3000	-	pF
C_{oss}	Output capacitance		-	74	-	
C_{rss}	Reverse transfer capacitance		-	5.8	-	
$C_{o(tr)}$(1)	Equivalent output capacitance time related	V_{DS} = 0 to 520 V, V_{GS} = 0 V	-	244	-	pF
$C_{o(er)}$(2)	Equivalent output capacitance energy related		-	70	-	pF
R_g	Gate input resistance	f = 1 MHz open drain	-	2.4	-	Ω
Q_g	Total gate charge	V_{DD} = 520 V, I_D = 15 A, V_{GS} = 0 to 10 V (see the Figure 17. Test circuit for gate charge behavior)	-	71	-	nC
Q_{gs}	Gate-source charge		-	18	-	
Q_{gd}	Gate-drain charge		-	30	-	

1. *$C_{o(tr)}$ is an equivalent capacitance that provides the same charging time as Coss while V_{DS} is rising from 0 V to the stated value.*
2. *$C_{o(er)}$ is an equivalent capacitance that provides the same stored energy as C_{oss} while V_{DS} is rising from 0 V to the stated value.*

Table 6. Switching times

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off delay time	V_{DD} = 400 V, I_D = 20 A, R_G = 4.7 Ω, V_{GS} = 10 V (see the Figure 18. Test circuit for inductive load switching and diode recovery times and Figure 21. Switching time waveform)	-	66	-	ns
$t_{r(v)}$	Voltage rise time		-	9	-	
$t_{c(off)}$	Crossing time off		-	9	-	
$t_{f(i)}$	Current fall time		-	13	-	

Table 7. Source-drain diode

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-	-	30	A
I_{SDM}[1]	Source-drain current (pulsed)		-	-	120	
V_{SD}[2]	Forward on voltage	I_{SD} = 30 A, V_{GS} = 0 V	-	-	1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 30 A, di/dt = 100 A/µs V_{DD} = 100 V (see the Figure 18. Test circuit for inductive load switching and diode recovery times)	-	382	-	ns
Q_{rr}	Reverse recovery charge		-	6.6	-	µC
I_{RRM}	Reverse recovery current		-	35	-	A
t_{rr}	Reverse recovery time	I_{SD} = 30 A, di/dt = 100 A/µs V_{DD} = 100 V, T_J = 150 °C (see the Figure 18. Test circuit for inductive load switching and diode recovery times)	-	522	-	ns
Q_{rr}	Reverse recovery charge		-	10.3	-	µC
I_{RRM}	Reverse recovery current		-	40	-	A

1. *Pulse width limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area for D²PAK and TO-220

Figure 2. Normalized transient thermal impedance for D²PAK and TO-220

Figure 3. Safe operating area for TO-247

Figure 4. Normalized transient thermal impedance for TO-247

Figure 5. Output characteristics

Figure 6. Transfer characteristics

Figure 7. Gate charge vs gate-source voltage

Figure 8. Static drain-source on-resistance

Figure 9. Capacitance variations

Figure 10. Output capacitance stored energy

Figure 11. Normalized gate threshold voltage vs temperature

Figure 12. Normalized on-resistance vs temperature

Figure 13. Drain-source diode forward characteristics

Figure 14. Normalized $V_{(BR)DSS}$ vs temperature

Figure 15. Switching energy vs gate resistance

Note: *E_{on} including reverse recovery of a SiC diode.*

3 Test circuits

Figure 16. Test circuit for resistive load switching times

AM01468v1

Figure 17. Test circuit for gate charge behavior

AM01469v1

Figure 18. Test circuit for inductive load switching and diode recovery times

AM01470v1

Figure 19. Unclamped inductive load test circuit

AM01471v1

Figure 20. Unclamped inductive waveform

AM01472v1

Figure 21. Switching time waveform

AM05540v2

4 Package information

To meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 D²PAK (TO-263) type A2 package information

Figure 22. D²PAK (TO-263) type A2 package outline

0079457_A2_27

Table 8. D²PAK (TO-263) type A2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.70	8.90	9.10
E2	7.30	7.50	7.70
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

Figure 23. D²PAK (TO-263) recommended footprint (dimensions are in mm)

4.2 TO-220 type A package information

Figure 24. TO-220 type A package outline

Table 9. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

4.3 TO-247 package information

Figure 25. TO-247 package outline

0075325_10

Table 10. **TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70
aaa		0.04	0.10

4.4 D²PAK packing information

Figure 26. D²PAK tape drawing (dimensions are in mm)

DM01095771_2

5 Ordering information

Table 11. **Order codes**

Order codes	Marking	Package	Packing
STB38N65M5	38N65M5	D²PAK	Tape and reel
STP38N65M5		TO-220	Tube
STW38N65M5		TO-247	

Revision history

Table 12. Document revision history

Date	Revision	Changes
22-Feb-2012	1	First release.
21-Jun-2012	2	Document status changed from preliminary data to production data. Added *Section 2.1: Electrical characteristics (curves)*.
05-Mar-2013	3	Added dv/dt value on *Table 2: Absolute maximum ratings*.
09-Apr-2014	4	The part number STF38N65M5 has been moved to a separate datasheet. Minor text changes.
19-Sep-2025	5	Updated Section 4: Package information. Minor text changes.

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